L	Hits	Search Text	DB	Time stamp
Number		(#20000107047#\\ PW	USPAT;	2003/08/26
3	1	("20020127847").PN.	US-PGPUB	11:15
21	42	(("phosphate ester" with (wetting or	USPAT;	2003/08/26
		surfactant)) and electroplating) and	US-PGPUB	11:20
24	0	(copper with zinc) (("phosphate ester" with (PEG or	USPAT;	2003/08/26
24	0	"polyethylene glycol") with (wetting or	US-PGPUB	11:22
		surfactant)) and electroplating) and		
0.5	0	(copper with zinc) (("phosphate ester" with (PEG or	USPAT;	2003/08/26
25	0	"polyethylene glycol") with (wetting or	US-PGPUB	11:22
		surfactant)) and electroplating) and		
		(copper and zinc)	USPAT;	2003/08/26
26	0	(("phosphate ester" with (PEG or "polyethylene glycol")) same (wetting or	US-PGPUB	11:22
		surfactant)) and electroplating and		
		(copper and zinc)	IICDAM.	2003/08/26
27	0	(("phosphate ester" same (PEG or "polyethylene glycol")) same (wetting or	USPAT;	11:23
		surfactant)) and electroplating and		
		(copper and zinc)	HCDAM.	2002/09/26
28	4	(("phosphate ester" same (PEG or "polyethylene glycol")) same (wetting or	USPAT; US-PGPUB	2003/08/26 11:23
		surfactant)) and electroplating		
29	0	(electroplating or electrochemical or	USPAT; US-PGPUB	2003/08/26
		electrodeposit\$5) with (bath or solution) with ("RE 610" or "RE-610")	US-FGFUB	11.34
30	55	(electroplating or electrochemical or	USPAT;	2003/08/26
		electrodeposit\$5) with (bath or solution)	US-PGPUB	11:38
		with (PEG or "polyethylene glycol" polyethyleneglycol)		
31	1	(((electroplating or electrochemical or	USPAT;	2003/08/26
		electrodeposit\$5) with (bath or	US-PGPUB	11:38
		solution)) same (PEG or "polyethylene glycol" polyethyleneglycol)) and ("RE		
		610" or RE610 or "RE-610")		
32	12		USPAT	2003/08/26
		"5098860" "5240497" "5262354" "5280154" "5288951" "5409587"		11:37
		"5466972" "5592024" "5654245").PN.		
33	3		USPAT; US-PGPUB	2003/08/26
		electrodeposit\$5)) same (PEG or "polyethylene glycol"	05-PGP0B	11.39
		polyethyleneglycol)) and ("RE 610" or		
		RE610 or "RE-610")	USPAT;	2003/08/26
35	0	((electroplating or electrochemical or electrodeposit\$5) and ((PEG or	US-PGPUB	11:40
		"polyethylene glycol" polyethyleneglycol)		
		same ("RE 610" or RE610 or "RE-610")))		
34	12	not electroless (electroplating or electrochemical or	USPAT;	2003/08/26
		electrodeposit\$5) and ((PEG or	US-PGPUB	11:40
		<pre>"polyethylene glycol" polyethyleneglycol) same ("RE 610" or RE610 or "RE-610"))</pre>		
_	411		USPAT;	2003/08/25
			US-PGPUB	16:14
-	129	"RE-610" with (wetting or surfactant)	USPAT; US-PGPUB	2003/08/25
_	27	("RE-610" with (wetting or surfactant))	USPAT;	2003/08/25
		and electroplating	US-PGPUB	16:16
-	7	(("RE-610" with (wetting or surfactant)) and electroplating) and (copper with	USPAT; US-PGPUB	2003/08/26 11:19
		zinc)		
_	6	"RE-610" with (PEG or "polyethylene	USPAT;	2003/08/25
	20	glycol") "RE 610" same (PEG or "polyethylene	US-PGPUB USPAT;	16:03 2003/08/25
-	28	glycol")	US-PGPUB	16:03
-	59	"RE 610" and (electroplating or "electro	USPAT;	2003/08/25
L		plating" or electrodeposit\$3)	US-PGPUB	16:15

	49	("RE 610" and (electroplating or "electro	USPAT;	2003/08/25
	'-	plating" or electrodeposit\$3)) not ("RE	US-PGPUB	16:15
		610" same (PEG or "polyethylene glycol"))		
l _	49	(("RE 610" and (electroplating or	USPAT;	2003/08/25
	''	"electro plating" or electrodeposit\$3))	US-PGPUB	16:15
		not ("RE 610" same (PEG or "polyethylene		
		glycol"))) not ("RE-610" with (PEG or		1
		"polyethylene glycol"))		
l _	23		USPAT;	2003/08/26
-	23	"electro plating" or electrodeposit\$3))	US-PGPUB	11:33
		not ("RE 610" same (PEG or "polyethylene	05 10102	
		glycol"))) not ("RE-610" with (PEG or		
		"polyethylene glycol"))) not (("RE-610"	ļ	
1	· ·	with (wetting or surfactant)) and		l i
	İ	electroplating)		
1	0		USPAT;	2003/08/25
-	"	"ZNCL.sub.2") with (metal adj (ion or	US-PGPUB	16:26
		source))) and (electroplating or "electro	05 10105	1 20:20
		plating" or electrodeposit\$3) and (copper	<u> </u>	1
1		with zinc)	· ·	1
1	0	''=' ' ' ' ' ' ' ' ' ' ' ' ' ' ' ' ' '	USPAT;	2003/08/25
-	1	"ZNCL.sub.2") with (metal adj (ion or	US-PGPUB	16:27
		source))) and (electroplating or "electro	05 10105	1 20.27
		plating" or electrodeposit\$3)		!
1	21	(("zinc dichloride" or "Zn Cl.sub.2" or	USPAT;	2003/08/25
-	21	"ZNCL.sub.2") same (metal adj (ion or	US-PGPUB	16:29
		source))) and (electroplating or "electro	05 10105	
İ		plating" or electrodeposit\$3)		i
	37		USPAT;	2003/08/25
1 -	37	"ZNCL.sub.2") same (metal adj (ion or	US-PGPUB	16:29
		source or salt))) and (electroplating or	05 10105	10.23
		"electro plating" or electrodeposit\$3)		
	26	(("zinc dichloride" or "Zn Cl.sub.2" or	USPAT;	2003/08/25
-	26	"ZNCL.sub.2") same (metal adj (salt)))	US-PGPUB	16:29
		and (electroplating or "electro plating"	35 13105	-3.2.
		or electrodeposit\$3)		
	9	I	USPAT;	2003/08/25
-	9	"ZNCL.sub.2") same (metal adj (salt)))	US-PGPUB	16:38
		and (electroplating or "electro plating"	33 23.03	-3.2.
1		or electropiating of electro plating or electrodeposit\$3) and (copper with		
		zinc)		
	4626	1 ===: ·	USPAT;	2003/08/25
-	4026	with (ion or salt) with zinc)	US-PGPUB	16:39
	11	(plating or solution or bath) same (metal	USPAT;	2003/08/25
1 -	11	with (ion or salt) with zinc with	US-PGPUB	16:40
		dichloride)	55 15155	
1	1	[dfclifotide)	L	II